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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









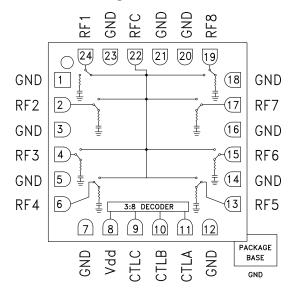


Typical Applications

The HMC253ALC4 is ideal for:

- Basestations & Repeaters
- WiMAX/WiBro & Fixed Wireless
- Cellular/3G Infrastructure
- CATV/DBS
- Military & Hi-Rel

Functional Diagram



Features

Ceramic, RoHS Compliant 4x4 mm SMT Package

Non-Reflective Topology
Low Insertion Loss: 1.6 dB

Single Positive Supply: Vdd = +5V

Integrated 3:8 TTL/CMOS Decoder: 0/+3V

General Description

The HMC253ALC4 is a non-reflective SP8T switch in a leadless RoHS compliant 4x4 mm ceramic SMT package featuring wideband operation from DC to 3.5 GHz. The switch offers a single positive bias and true TTL/CMOS compatibility enabling it to operate with 0/+3V control and a +5V supply. A 3:8 decoder is integrated on the switch requiring only 3 control lines and a positive bias to select each path. The HMC253ALC4 SP8T will replace multiple configurations of SP4T and SPDT MMIC switches.

Electrical Specifications,

$T_{A} = +25^{\circ}$ C, For TTL Control and Vdd = +5V in a 50 Ohm system

Parameter		Frequency	Min.	Тур.	Max.	Units
Insertion Loss		DC - 2.0 GHz DC - 3.0 GHz DC - 3.5 GHz		1.1 1.6 1.9	1.5 2.0 2.4	dB dB dB
Isolation		DC - 2.0 GHz DC - 3.0 GHz DC - 3.5 GHz	38 34 30	43 39 35		dB dB dB
Return Loss	"On State"	0.3 - 3.0 GHz 0.3 - 3.5 GHz		13 10		dB dB
Return Loss (RF1-8)	"Off State"	0.3 - 3.5 GHz 0.5 - 3.5 GHz		10 14		dB dB
Input Power for 1 dB Compression		0.5 - 3.5 GHz	20	24		dBm
Input Third Order Intercept (Two-Tone Input Power = +10 dBm Each Tone)		0.5 - 3.5 GHz	40	43		dBm
Switching Characteristics		0.3 - 3.5 GHz				
tRISE, tFALL (10/90% RF) tON, tOFF (50% CTL to 10/90% RF)				30 100		ns ns

HMC253ALC4* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS 🖵

View a parametric search of comparable parts.

EVALUATION KITS

· HMC253ALC4 Evaluation Board

DOCUMENTATION

Data Sheet

 HMC253ALC4: GaAs MIMIC SP8T Non-Reflective Switch, DC-3.5 GHz Data Sheet

TOOLS AND SIMULATIONS 🖳

HMC253ALC4 S-Parameters

DESIGN RESOURCES

- HMC253ALC4 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

DISCUSSIONS •

View all HMC253ALC4 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

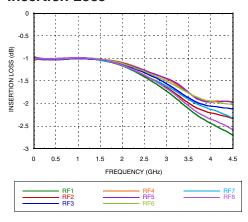
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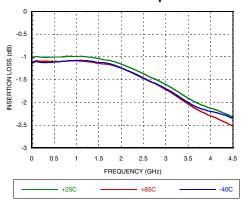




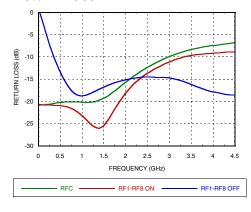
Insertion Loss



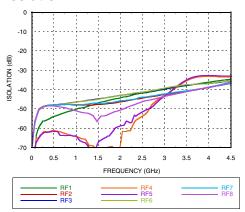
Insertion Loss vs. Temperature



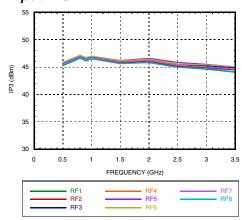
Return Loss



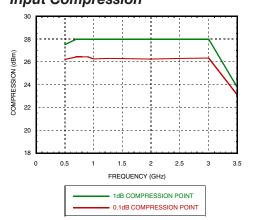
Isolation



Input IP3



Input Compression







Bias Voltage & Current

Vdd Range = +5 Vdc ± 10%			
Vdd (Vdc)	Idd (Typ.) (mA)	Idd (Max.) (mA)	
+5	4.5	7.5	

TTL/CMOS Control Voltages

State	Bias Condition
Low	0 to +0.8 Vdc @ <1 μA Typ.
High	+2.0 to +5 Vdc @ 60 μA Typ.

Truth Table

Control Input			Signal Path State
А	В	С	RFCOM to:
Low	Low	Low	RF1
High	Low	Low	RF2
Low	High	Low	RF3
High	High	Low	RF4
Low	Low	High	RF5
High	Low	High	RF6
Low	High	High	RF7
High	High	High	RF8

NOTE:

DC Blocking capacitors are required at ports RFC and RF1, 2, 3, 4, 5, 6, 7, 8.



Absolute Maximum Ratings

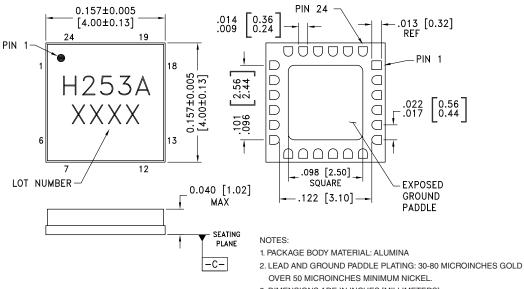
Bias Voltage Range (Port Vdd)	+7.0 Vdc
Control Voltage Range (A, B, C)	-0.5V to Vdd +1Vdc
Channel Temperature	150 °C
Thermal Resistance (channel to package ground paddle)	
Through Path	183 °C/W
Termination Path	274 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
Maximum Input Power (Vdd = +5V)	
Through Path	+20 dBm (0.05 - 0.5 GHz)
Terminated Path	+25 dBm (0.5 - 3.5 GHz) +20 dBm (0.05 - 0.5 GHz) +23.5 dBm (0.5 - 3.5 GHz)
ESD Sensitivity (HBM)	Class 1A





Outline Drawing

BOTTOM VIEW



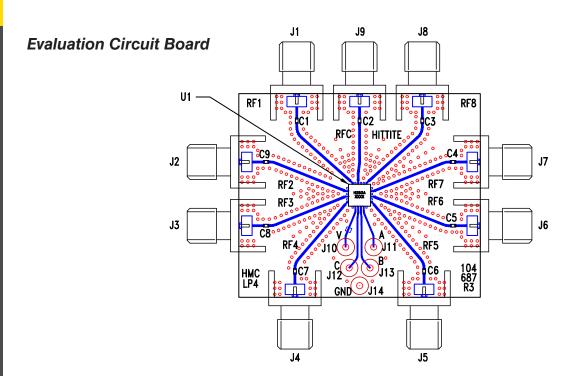
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM -C-
- $6.\,\mathrm{ALL}$ GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 3, 5, 7, 12, 14, 16, 18, 20, 21, 23	GND	Package bottom has exposed metal paddle that must also be connected to RF ground.	○ — ○ GND
2, 4, 6, 13, 15, 17, 19, 22, 24	RF1 - RF8 & RFC	This pin is DC coupled and matched to 50 Ohms. Blocking capacitors are required.	
8	Vdd	Supply Voltage +5 Vdc ±10%	VddO———————————————————————————————————
9	CTLC		Vdd
10	CTLB	See truth table and control voltage table.	· — — — — — — — — — — — — — — — — — — —
11	CTLA		<u> </u>







List of Materials for Evaluation PCB EV1HMC253ALC4 [1]

Item	Description	
J1 - J9	PCB Mount SMA Connector	
J10 - J14	DC Pin	
C1 - C9	100 pF Capacitor, 0402 Pkg.	
U1	HMC253ALC4 SP8T Switch	
PCB [2]	104687 Eval Board	

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should be generated with proper RF circuit design techniques. Signal lines at the RF ports should have 50 ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown above. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.